

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1696	100.0	3.2
			Subtotal	0.1696	100	3.2
Die		Lead Dioxide (PbO2)	1309-60-0	0.0019	1.06	0.03586
		Silicon (Si)	7440-21-3	0.17741	98.94	3.3473
			Subtotal	0.17931	100	3.38316
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.378	100.0	26
			Subtotal	1.378	100	26
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02733	0.04	0.5156
	Copper alloy	Iron (Fe)	7439-89-6	0.06832	0.1	1.289
	Copper alloy	Copper (Cu)	7440-50-8	68.22158	99.86	1,287.1954
			Subtotal	68.31723	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.5937	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.77002	16.0	90
	Filler	Silica fused	60676-86-0	22.35945	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.08944	0.3	1.6875
			Subtotal	29.81261	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00716	5.0	0.13516
	Lead alloy	Silver (Ag)	7440-22-4	0.00358	2.5	0.06758
	Lead alloy	Lead (Pb)	7439-92-1	0.13252	92.5	2.5004
			Subtotal	0.14326	100	2.70314
			Total	100.00001	100	NaN

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